

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

*IFW*

Applicant: Vassoudevane Lebonheur et al.

Title: MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND  
PROCESS OF MAKING SAME

Docket No.: 884.862US1

Filed: June 30, 2003

Examiner: Victor A. Mandala



Serial No.: 10/612,764

Due Date: October 27, 2005

Group Art Unit: 2826

**MS Amendment**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

☒ Return postcard.

☒ Amendment and Response Under 37 C.F.R. 1.111 (15 pgs.).

If not provided in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

By: *Ann M. McCrackin*  
Atty: Ann M. McCrackin  
Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 21 day of August, 2005.

*John D. Spataro-Wenthall*  
Name

*John D. Spataro-Wenthall*  
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)



N 10/612,764

PATENT

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Applicant:	Vassoudevane Lebonheur et al.	Examiner:	Victor A Mandala
Serial No.:	10/612,764	Group Art Unit:	2826
Filed:	June 30, 2003	Docket No.:	884.862US1
Title:	MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND PROCESS OF MAKING SAME		
Assignee:	Intel Corporation	Customer No:	21186

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AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

This responds to the Office Action mailed on July 27, 2005. Please amend the above-identified patent application as follows.